Meeting – CW 43 (Oct 24th 25th)

Assuming that until the meeting the following items are in the master branch, i.e., code review(s) during the next days:

- Feature/pedestal scan analysis
- Feature/offsets memdump
- archiver
- adc_curve-smallimprovements
- lab_offsets_image
- elog_gransummary

Hardware Agenda (Lab visit and discussions)

- grounding
- cooling (plastic clamps, vacuum)
- L1 module handling:
    - Connection L1 modules which will go to Göttingen;
    - Basic measurements: pedestal and noise
    - …

Software Agenda

A) Discussion Part

1) Source measurements
    a. What do we want to measure? Cd-109, Sr-90? All sensitive area, how many hits? How much statistic is required?
    b. Define the analysis – what analyses should be performed?
        i. Landau distribution
        ii. Masking of noisy pixel/ADCs
        iii. Peak-to-valley, ring finding
        iv. sw-DCD regions
        v. insensitive areas (due to production issues, e.g., partially irradiated by X-ray inspection, etc.)
        vi. How to compare results between different modules?
        vii. What of these analyses are relevant for elog/grading?

2) What information is relevant for the elog, in particular for final grading for the different module tests

3) Ladder characterization; how to handle entries in elog; how to connect to modules

4) Discussion of temperature issues, collect ideas how to

5) Development of verification of DHP memories (switcher seq, pedestal, offsets) – correct writing via JTAG;

6) How to grade – if not already discussed in the last meetings – from elog results?

B) Practical Part

1) Source measurement
    a. Implement measure script to perform the scan over the entire sensitive area, i.e., include motor stage/stepper
    b. Implement the analysis (will take some time)

2) Implementation of reliable temperature measurement

3) Implementation of verification of DHP memories

4) Burn-In test, like emergency shutdowns, etc….